



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	03/24/2015
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	GIUSEPPE VITALI PALMA	Representative Title	AMS/IPD Materials Declaration Champion)
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	8HST*TWU056D	A	BO2A	03/24/2015
Amount	UoM	Unit type	ST ECOPACK Grade	
70.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SMC	4.15X2.76X1.94	1	J bend	
Comment	Package: SMA; MD valid for SMA6J48A-TR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	8HST*TWU056D							
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)		
die (s)	Other inorganic materials	1.609	mg	supplier	die	Silicon (Si)	7440-21-3		1.573	mg	977626	22471		
						Aluminium (Al)	7429-90-5		0.012	mg	7458	171		
Leadframe	Copper & its alloys	29.015	mg	supplier	alloy	back side metallization	Gold (Au)	7440-57-5	0.004	mg	2486	57		
							Nickel (Ni)	7440-02-0	0.02	mg	12430	286		
							Copper (Cu)	7440-50-8	28.977	mg	998690	413957		
							Iron (Fe)	7439-89-6	0.029	mg	999	414		
							Iron Phosphide (FeP)	26508-33-8	0.009	mg	310	129		
Die attach		1.634	mg	JIG R	Solder paste	Lead (Pb)	7439-92-1	7a-Lead in high me	1.527	mg	934517	21814		
							supplier	Solder paste	Silver (Ag)	7440-22-4	0.025	mg	15300	357
									Tin (Sn)	7440-31-5	0.082	mg	50184	1171
Bonding wire	Other inorganic materials	11.481	mg	supplier	Frame clip	Copper (Cu)	7440-50-8		11.481	mg	1000000	164014		
encapsulation	Other organic materials	25.52	mg	supplier	mold compound	Silica, vitreous	60676-86-0		19.396	mg	760031	277086		
							Phenol resin	9003-35-4	1.531	mg	59992	21871		
							Carbon black	1333-86-4	0.204	mg	7994	2914		
							Epoxy Cresol Novolak	29690-82-2	2.603	mg	101998	37186		
							Metal hydroxide	Proprietary	0.51	mg	19984	7286		
	Others	Proprietary	1.276	mg	50000	18229								
connections coating	Other inorganic materials	0.741	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.741	mg	1000000	10586		